Abstract

An object is to provide a fixing carrier, a fixing carrier manufacturing method, a method of using the fixing carrier and a substrate storage container, which provide proper shipment of items to be loaded that are prone to warp and crack. A base 2 having rigidity is hollowed on its surface and formed with a sectioned space 3 laminated and covered by a supporting layer 8 that supports semiconductor wafer W, multiple projections 4 that are formed in the sectioned space and supports supporting layer 8 in contact therewith and an exhaust passage 6 that is bored through base 2 and draws air out of sectioned space 3 covered by supporting layer 8. Since semiconductor wafer W that is prone to warp and crack is supported by supporting layer 8 of a fixing carrier 1 and accommodated in the container body of a substrate storage container, instead of being kept directly in the container, so it is possible to achieve safe and proper shipment between factories.